IPC ASSOCIATION ELECTRONIC	Material Composition Declaration © Copyright 2005. IPC, Bannockburn, Illinois. All rights reserved under both international and Pan-American copyright conventions.				This document is a declaration of the substances within the manufacturer listed item. Note: if the item is an assembly with lower level parts, the declaration encompasses all lower level materials for which the manufacturer has engineering responsibility.										
1752-21.1					Form Type Distribute	Declaration Class * Class 6 - RoHS Yes/No, Homogeneous Mater				eous Materi	ials and Mfg Information				
Supplie	r Information														
Company	name*	Company unique ID			1	Unique ID Authority					Response Date*				
onsemi												2025-09-06			
Contact N	lame		Title - Contact]	Phone - Contact*				Email - Contact*				
Product-l	Env-Stewards		Product Enviro Compliance				NA					Product-Env-Stewards@onsemi.com			
Authorize	ed Representative*	Title - Representative]	Phone - Representative*				Email - Representative*					
Product-l	Env-Stewards	Product Enviro Compliance				NA				Product-Env-Stewards@onsemi.com					
	Requester Item Number Mfr Item		Number Mfr Item Name				Effective Dat	e Version	Version Manufacturing Site		ring Site	Weight*		UOM	Unit Type
		DFB2005	5	BR TS6P GPPN 20A 50V			2025-09-06		r	TSCBE		7	671.0	mg	Each
Manufa	cturing Proccess Information	tion													
	Terminal Plating / Grid Array Material		Cerminal Base Alloy J-STD-02		-STD-020 MSL	_ Rating	Peak Process Body Ter		Temperatu	perature Max Time at Peak		Temperature Number of Re		ber of Reflow Cyc	eles
	Matte Tin (Sn) - annealed		CU Alloy NA			0 C		30 seco		second	ls 3				
Comments	3														
				<u> </u>		·					·				·
or more	information regarding material	composition	please refer to	page 3										·	

RoHS Material Composition Declaration			Declaration Type *	Detailed						
Directive 2015/863/EU amending RoHS Directive 2011/65/EU RoHS Definition: Quantity limit of 0.01% by mass (100 PPM) in homogeneous material for Cadmium and quantity limit of 0.1% by mass (1000 PPM) in homogeneous material for Cadmium and quantity limit of 0.1% by mass (1000 PPM) in homogeneous material for: Lead (Pb), Mercury (Hg), Hexavalent Chromium (Cr6+), Polybrominated Biphenyls (PBB), Polybrominated Diphenyl Ethers (PBDE), and Bis(2-ethylhexyl) phthalate (DEHP), Benzyl-butyl phthalate (BBP), Dibutyl phthalate (DBP), Diisobutyl phthalate (DIBP).										
Please indicate whether any homogeneous material (as defined by the RoHS Directive, EU 2011/65/EU and implemented by the laws of the European Union member states) of the part identified on this form contains lead, mercury, cadmium, hexavalentchromium, polybrominated biphenyls and/or polybrominated diphenyl ethers (each a "RoHS restricted substance") in excess of the applicable quantity limit identified above. If a homogeneous material within the part contains a RoHS restricted substance inexcess of an applicable quantity limit, please indicate below which, if any, RoHS exemption you believe may apply. If the part is an assembly with lower level components, the declaration shall encompass all such components. Supplier certifies that it gathered the information it provides in this form using appropriate methods to ensure its accuracy and that such information is true and correct to the best of its knowledges and belief, as of the date that Supplier completes this form. Supplier acknowledges that Company will rely on this certification in determining the compliance of its products with European Union member state laws that implement the RoHS Directive. Company acknowledges that Supplier may have relied on information provided by others in completing this form, and that Supplier may not have independently verified such information. However, in situations where Supplier has not independently verified information provided by others, Supplier agrees that, at a minimum, its paragraph. If the Company and the Supplier supplier have provided certifications regarding their contributions to the part, and those certifications are at least as comprehensive as the certification in this paragraph. If the Company and the Supplier enter into a written agreement with respect to the identified part, the terms and conditions of that agreement, including any warranty rights and/or remedies provided as part of that agreement, will be the sole and exclusivesource of the Supplier's Standard Terms and Conditions of Sale applicable to suc										
RoHS Declaration * 4 - Item(s) does not contain RoHS restricted substance	s per the definition above except for selected exemp	tions Supplier Acceptance	* Accepted						
Exemption: 7a: Lead in high melting temperature type solders (i.e. lead based solder alloys containing 85% by weight or more lead).										
Exemption List Version	EL-2011/534/EU									
Declaration Signature										
Instructions: Complete all of the required fields on all pages of this form. Select the "Accepted" on the Supplier Acceptance drop-down. This will display the signature area. Digitally sign the declaration (if required by the Requester) and click on Submit Form to have the form returned to the Requester.										
Supplier Digital Signature Ra	astislav Drska	-En								

Homogeneous Material Composition Declaration for Electronic Products

SubItem Instructions: The presence of any JIG Level A or B substances must be declared. [1] indicate the subpart in which the substance is located, [2] provide a description of the homogeneous material [3], enter the weight of the homogeneous material.

Substance Instructions: [A] select the Level (JIG A, JIG B, Requester or Supplier) [B] select the substance category (JIG or Requester) or enter a value (Supplier). [C] select the substance (JIG) or enter the substance and CAS (Other). [D] select a RoHS exemption, if applicable [E] enter the weight of the substance or the PPM concentration [F] Optionally enter the positive (+) and negative (-) tolerance in percent (Note: percent tolerance values are expected to cover a 3 sigma range of distribution unless otherwise noted).

Homogeneous Material	Weight	Unit of Measure	Level	Substance	CAS	Exempt	Weight	Unit of Measure
Die Attach Solder	200.0	mg	Supplier	Silver (Ag)	7440-22-4		5	mg
			A	Lead (Pb)	7439-92-1	7a	185	mg
			Supplier	Tin (Sn)	7440-31-5		10	mg
Jumper	60.4	mg	Supplier	Iron (Fe)	7439-89-6		0.05	mg
			Supplier	Copper (Cu)	7440-50-8		60.34	mg
			Supplier	Phosphorus (P)	7723-14-0		0.01	mg
Lead Frame	2315.0	mg	Supplier	Iron (Fe)	7439-89-6		1.852	mg
			Supplier	Copper (Cu)	7440-50-8		2312.6851	mg
			Supplier	Phosphorus (P)	7723-14-0		0.463	mg
Mold Compound-Black	4807.0	mg	В	Brominated Bisphenol A Diglycidyl Ether	40039-93-8		96.14	mg
			Supplier	Ortho Cresol Novolac Resin	29690-82-2		721.05	mg
			В	Antimony Trioxide (Sb2O3)	1309-64-4		96.14	mg
			Supplier	Carbon Black (C)	1333-86-4		48.07	mg
			Supplier	Phenolic Resin (Novolac)	9003-35-4		480.7	mg
			Supplier	Silica Crystalline (SiO2)	14808-60-7		3364.8999	mg
Plating	248.6	mg	Supplier	Tin (Sn)	7440-31-5		248.6	mg
Silicon Dice	40.0	mg	Supplier	Silicon (Si)	7440-21-3		39.992	mg
			В	Nickel (Ni)	7440-02-0		0.004	mg
			Supplier	Gold (Au)	7440-57-5		0.004	mg